

WHAT IS CLAIMED IS:

1. A high-frequency power amplifier comprising:
 - a multilayer substrate formed by laminating a plurality of
5 dielectric layers;
 - a wiring prohibited area provided on at least one of a
obverse side and a reverse side of said multilayer substrate;
 - a first strip conductor provided within said multilayer
substrate;
 - 10 a second strip conductor provided such that its position
in a lamination direction of said multilayer substrate is
different from that of said first strip conductor;
 - a via for electrically connecting said first strip
conductor and said second strip conductor; and
 - 15 a first grounding conductor and a second grounding
conductor disposed sequentially in said lamination direction of
said multilayer substrate and sandwiching said first strip
conductor and said second strip conductor;
 - wherein at least one of said first grounding conductor and
20 said second grounding conductor includes:
 - a first grounding conductor portion provided for said
wiring prohibited area; and
 - a second grounding conductor portion provided for an area
other than said wiring prohibited area such that a position of
25 said second grounding conductor portion in said lamination
direction of said multilayer substrate is different from that of
said first grounding conductor portion.
2. The high-frequency power amplifier according to claim 1,
30 wherein said wiring prohibited area includes:
 - a first wiring prohibited area provided on said obverse
side of said multilayer substrate; and

a second wiring prohibited area provided on said reverse side of said multilayer substrate such that said second wiring prohibited area is disposed at a position at which it overlaps said first wiring prohibited area as viewed in said lamination direction of said multilayer substrate;

wherein a length of said first wiring prohibited area in said lamination direction of said multilayer substrate is different from that of said second wiring prohibited area.

10 3. The high-frequency power amplifier according to claim 1, wherein said wiring prohibited area includes:

a first wiring prohibited area provided on said obverse side of said multilayer substrate; and

a second wiring prohibited area provided on said reverse side of said multilayer substrate such that said second wiring prohibited area is disposed at a position at which it does not overlap said first wiring prohibited area as viewed in said lamination direction of said multilayer substrate.

20 4. The high-frequency power amplifier according to claim 1, wherein one end of said first grounding conductor portion is formed such that it runs along a periphery of said via as viewed in said lamination direction of said multilayer substrate.

25 5. A high-frequency power amplifier comprising:

a multilayer substrate formed by laminating a plurality of dielectric layers;

a first wiring prohibited area provided on a obverse side of said multilayer substrate;

30 a second wiring prohibited area provided on a reverse side of said multilayer substrate such that said second wiring prohibited area is disposed at a position at which it overlaps

said first wiring prohibited area as viewed in a lamination direction of said multilayer substrate;

a strip conductor disposed within said multilayer substrate; and

5 a first grounding conductor and a second grounding conductor disposed sequentially in said lamination direction of said multilayer substrate and sandwiching said strip conductor;

wherein a length of said first wiring prohibited area in said lamination direction of said multilayer substrate is equal
10 to that of said second wiring prohibited area;

wherein said first grounding conductor includes:

a first grounding conductor portion provided for said first wiring prohibited area; and

a second grounding conductor portion provided for an area
15 on said obverse side of said multilayer substrate such that a position of said second grounding conductor portion in said lamination direction of said multilayer substrate is different from that of said first grounding conductor portion, said area being other than said first wiring prohibited area; and

20 wherein said second grounding conductor includes:

a third grounding conductor portion provided for said second wiring prohibited area; and

a fourth grounding conductor portion provided for an area
25 on said reverse side of said multilayer substrate such that a position of said fourth grounding conductor portion in said lamination direction of said multilayer substrate is different from that of said third grounding conductor portion, said area being other than said second wiring prohibited area.